Abstract

This invention relates to a pressure transmission apparatus for bonding a plurality of chips (13) to a substrate (12) with:

- a pressure body (2) for applying a bonding force which acts in the bonding direction (B) to the chip (13), the pressure body (2) having a first pressure side (2o) and an opposite second pressure side (2f) which run transversely to the bonding direction (B),
- fixing means (8, 8', 8") which can be attached to the periphery of the pressure transmission apparatus (1) for fixing of the pressure transmission apparatus (1) on a retaining body (9) in the bonding direction (B), and
- a sliding layer (3) for sliding motion of the pressure body (2) transversely to the bonding direction (B).

Figure 2a